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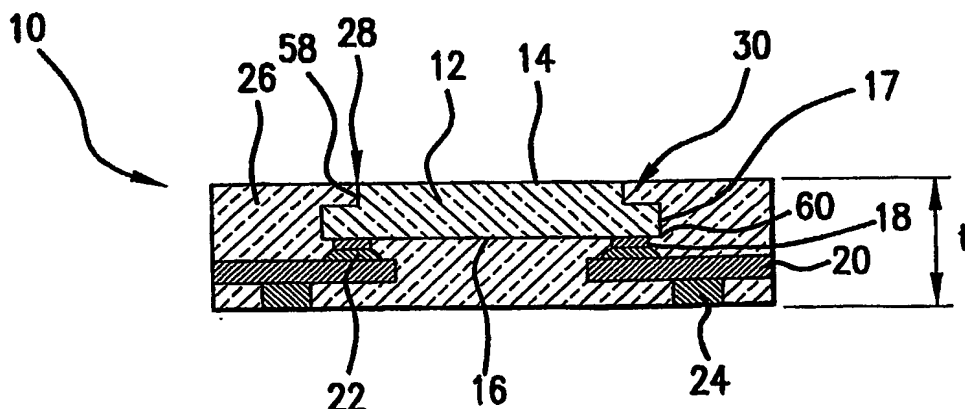
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(54) Title: PACKAGE HAVING EXPOSED INTEGRATED CIRCUIT DEVICE



(57) Abstract: A package (10) includes an integrated circuit device (12) having an electrically active surface (16) and an opposing backside surface (14). A dielectric molding resin (26) at least partially encapsulates the integrated circuit die and the plurality of electrically conductive leads (20) with the backside surface (14) and the plurality of electrical contacts (24) being exposed on opposing sides of the package (10). Features (30) are formed into electrically inactive portions of the integrated circuit die (12) to seal moisture paths and relieve packaging stress. The features (30) are formed by forming a trough (54) partially through the backside (56) of the wafer (40) in alignment with a saw street (48), the trough (54) having a first width; and forming a channel (62) extending from the trough (54) to the electrically active face (42) to thereby singulate the integrated circuit device member, the channel (62) having a second width that is less than the first width. (Drawing Figure 2)

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